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(71) Applicant (for all designated States except US): **MICRON TECHNOLOGY, INC.** [US/US]; 8000 S. Federal Way, Boise, ID 83707-0006 (US).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **AGRANOV, Genadiy, A.** [US/US]; 5371 N. Riffle Way, Boise, ID 83714 (US). **KARASEV, Igor** [RU/US]; 1538 Maurice Ln. #77, San Jose, CA 95129 (US).

(74) Agent: **D'AMICO, Thomas, J.**; Dickstein Shapiro LLP, 1825 Eye Street, NW, Washington, DC 20006-5403 (US).

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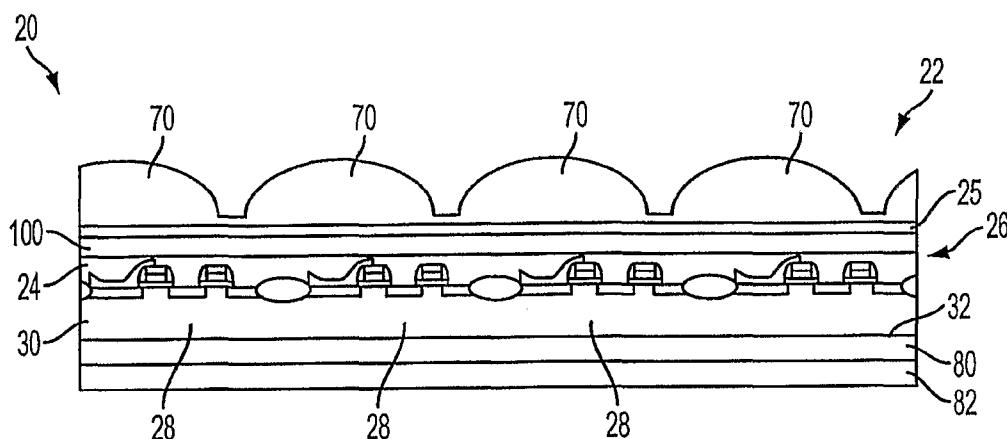
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(54) Title: BACKSIDE SILICON WAFER DESIGN REDUCING IMAGE ARTIFACTS FROM INFRARED RADIATION



(57) Abstract: Imaging devices having reduced image artifacts are disclosed. The image artifacts in the imaging devices are reduced by redirecting, absorbing or scattering IR radiation that passes through the imaging device substrate away from dark pixels.

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